

#### **Description**

The HSW2N15 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

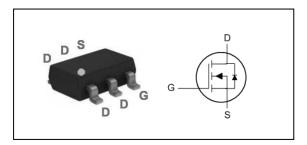
The HSW2N15 meet the RoHS and Green Product requirement with full function reliability approved.

## **Product Summary**

V <sub>DS</sub>	150	٧
R <sub>DS(ON),typ</sub>	380	mΩ
lo	1.4	Α

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

#### **SOT23-6L Pin Configuration**



#### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	150	V
V <sub>G</sub> s	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	1.4	А
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	0.88	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	5.6	А
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1.56	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol Parameter		Тур.	Max.	Unit
Reja	Thermal Resistance Junction-ambient(steady state) <sup>1</sup>		80	°C/W
	Thermal Resistance Junction-ambient(t<10s) <sup>1</sup>		43	°C/W





## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage V <sub>GS</sub> =0V , I <sub>D</sub> =250uA		150		-	V	
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.122		V/°C	
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =1A		380	480	mΩ	
R <sub>DS(ON)</sub>		$V_{GS}$ =6 $V$ , $I_D$ =0.5 $A$		410	520	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2	3	4	V	
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS=VDS, ID =250UA		-4.84		mV/°C	
1	Drain Source Lookage Current	V <sub>DS</sub> =150V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =150V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			10	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
Qg	Total Gate Charge (10V)			8.3			
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =75V , V <sub>GS</sub> =10V , I <sub>D</sub> =1A		2		nC	
$Q_{gd}$	Gate-Drain Charge			2.3			
T <sub>d(on)</sub>	Turn-On Delay Time			8.3			
Tr	Rise Time	$V_{DD}$ =75 $V$ , $V_{GS}$ =10 $V$ , $R_{G}$ =10 $\Omega$		5.8			
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A		15		480 mΩ 520 mΩ 4 V mV/°C 1 uA 10 nA nC nS pF	
Tf	Fall Time			8			
C <sub>iss</sub>	Input Capacitance			350			
Coss	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		33		pF	
Crss	Reverse Transfer Capacitance			25			

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			1.4	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V
trr	Reverse recovery time			43		ns
Qrr	Reverse recovery Charge	Is=1A,di/dt=100A/us		38		nC

#### Note

<sup>1.</sup> The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

<sup>3.</sup>The power dissipation is limited by 150°C junction temperature

<sup>4.</sup> The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.





### **Typical Characteristics**

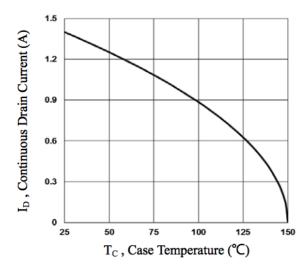


Fig.1 Continuous Drain Current vs. Tc

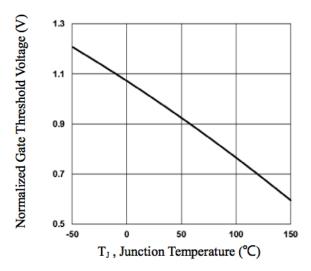


Fig.3 Normalized  $V_{th}$  vs.  $T_J$ 

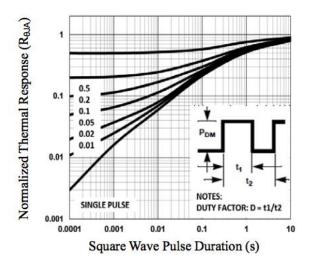


Fig.5 Normalized Transient Impedance

# N-Ch 150V Fast Switching MOSFETs

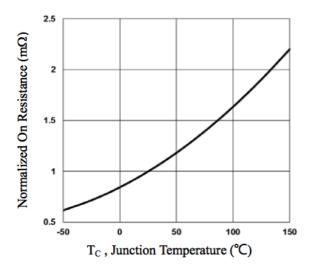


Fig.2 Continuous Drain Current vs. Tc

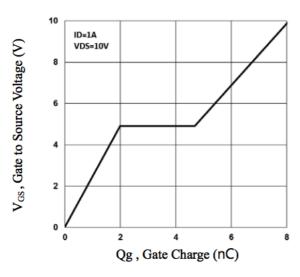


Fig.4 Gate-Charge Waveform

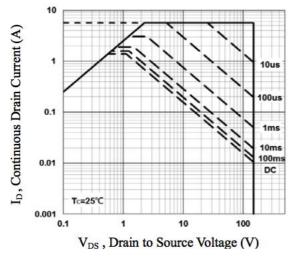


Fig.6 Maximum Safe Operation Area





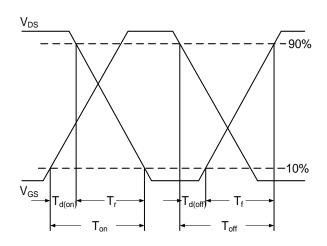


Fig.7 Switching Time Waveform

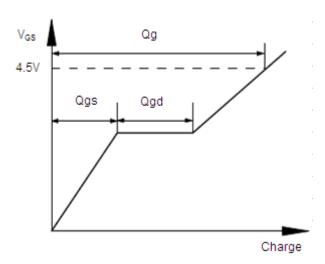
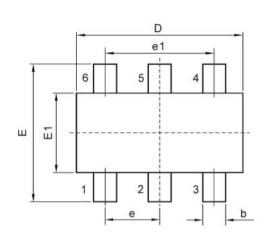
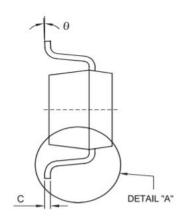


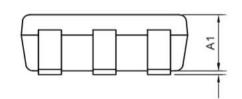
Fig.8 Gate Charge Waveform

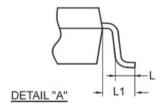


# SOT23-6L Package Outline Dimensions









CVMDOLC	MILLIMETERS		INCHES	
SYMBOLS	MIN	MAX	MIN	MAX
D	2.692	3.099	0.106	0.122
E	2.591	3.000	0.102	0.118
E1	1.397	1.803	0.055	0.071
е	0.950 REF.		0.037 REF.	
e1	1.900 REF.		0.075 REF.	
b	0.300	0.500	0.012	0.020
С	0.080	0.200	0.003	0.008
Α	0.000	0.100	0.000	0.004
A1	0.700	1.200	0.028	0.048
L	0.300	0.600	0.012	0.024
L1	0.600 REF.		0.023 REF.	
θ	0°	9°	0°	9°

## **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by HUASHUO manufacturer:

Other Similar products are found below:

614233C 648584F NTNS3A92PZT5G IRFD120 IRFF430 JANTX2N5237 2N7000 2SK2464-TL-E FCA20N60\_F109 FDZ595PZ AOD464 2SK2267(Q) 2SK2545(Q,T) 405094E 423220D MIC4420CM-TR VN1206L 614234A 715780A SSM6J414TU,LF(T 751625C IPP60R600P6XKSA1 RJK60S5DPK-M0#T0 BSC884N03MS G BSF024N03LT3 G PSMN4R2-30MLD TK31J60W5,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 EFC2J004NUZTDG FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE2384 NTE2969 NTE6400A DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 SSM6P54TU,LF DMP22D4UFO-7B IPS60R3K4CEAKMA1 DMN1006UCA6-7 DMN16M9UCA6-7 STF5N65M6 STU5N65M6 C3M0021120D DMN13M9UCA6-7 BSS340NWH6327XTSA1